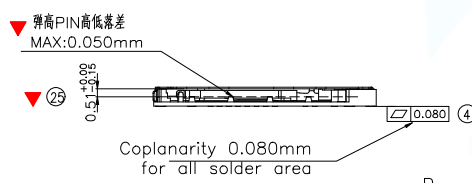
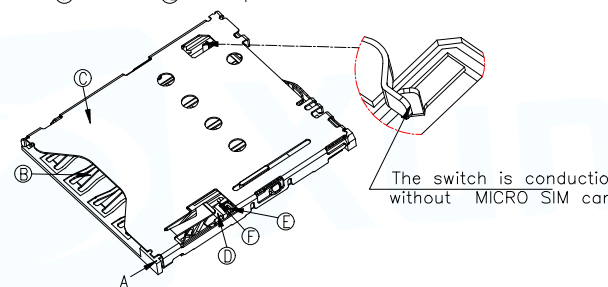
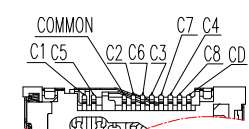
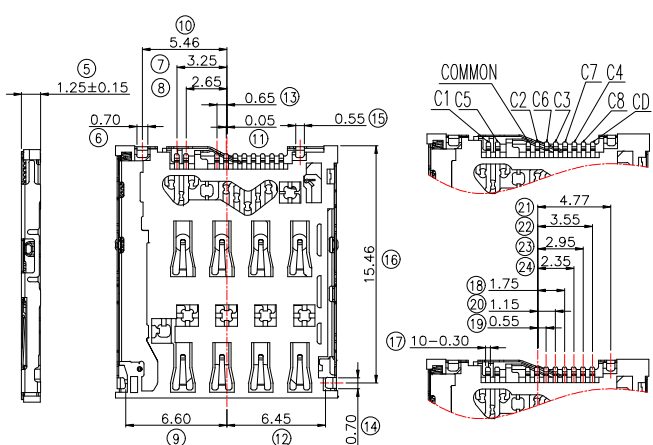
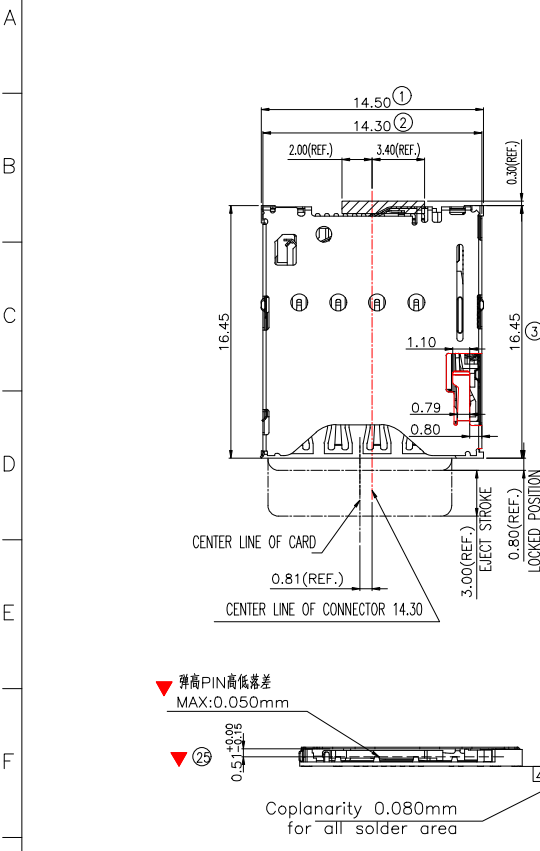
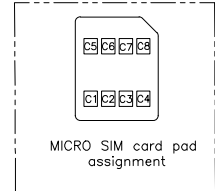
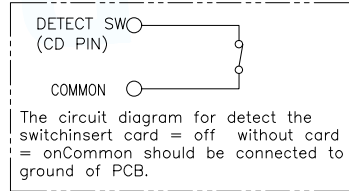


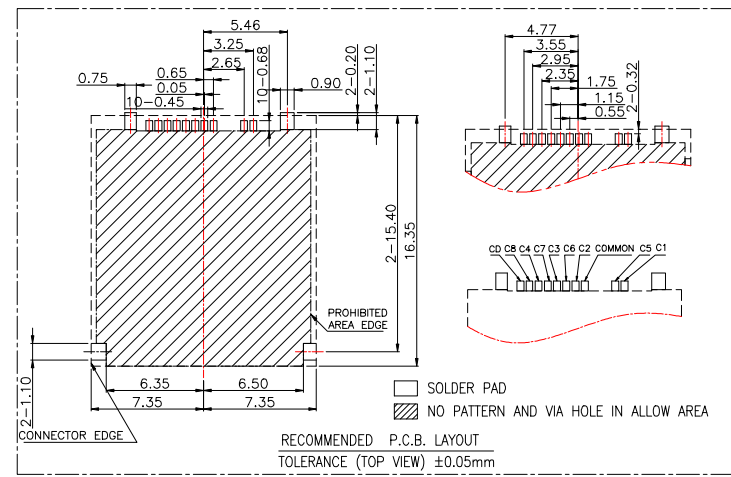
MAPX	MODIFICATION	DATE	DRAW	APPROVE



- SPECIFICATIONS:
- ELECTRICAL CHARACTERISTICS:
 - CURRENT RATING: 1A
 - CONTACT RESISTANCE:
 - 1-2-1. 100mΩ MAX. (INITIAL) (FOR C1/C2/C3/C4/C5/C6/C7/C8)
 - 1-2-2. 500mΩ MAX. (INITIAL) (FOR CD/COMMON)
 - DIELECTRIC WITHSTANDING VOLTAGE: 500V AC FOR ONE MINUTE.
 - INSULATION RESISTANCE: 100MΩ MIN. BY 500V DC.
 - MECHANICAL CHARACTERISTICS:
 - LIFE TEST: 5000 CYCLES MIN.
 - ENVIRONMENTAL CHARACTERISTICS:
 - SALT MIST TEST CONDITION: PER IEC 68-2-52, SEVERITY(3)
 - OPERATING TEMPERATURE: -30°~+80°
 - TO CONFORM TO SINGATRON HAZARDOUS SUBSTANCE FREE SPEC.
 - RoHS COMPLIANT PRODUCT.
 - HALOGEN FREE PRODUCT IDENTIFICATION MARK: ON PACKAGING:
 - FOR REFLOW SOLDERING LEAD-FREE PROCESS.
 - PACKAGING: TAPE & REEL.
 - OTHER GENERAL SPEC. TO REFER "2SM2019 SERIES SPEC."
 - FOR REFLOW SOLDERING LEAD-FREE PROCESS.
 - PACKAGING: TAPE & REEL.



PIN NO.	PIN ASSIGNMENT
C1	SUPPLY VOLTAGE(VCC)
C2	RESET(RST)
C3	CLOCK(CLK)
C4	RESERVED FOR FUTURE USE(RFU)
C5	GROUND(GND)
C6	PROGRAMMING VOLTAGE(VPP)
C7	I/O
C8	RESERVED FOR FUTURE USE(RFU)



F	LINK	1	STAINLESS STEEL T=0.10	N/A
E	SPRING	1	SWP	NICKEL PLATING
D	SLIDE	1	HIGH TEMP.THERMOPLASTIC,UL94V-0 AND STAINLESS STEEL	BLACK
C	SHELL	1	SUS 301 1/2H T=0.1	NICKEL PLATING
B	CONTACT	1	C5210 EH T=0.10 4SM2019-002002	3u" GOLD PLATING ONCONTACT AREA AND SOLDER AREA, 50u" MIN NICKEL UNDER PLATING
A	HOUSING	1	LCP+35%GF S475 UL94V-0	BLACK

MANUFACTURE DWG

东莞市讯普电子科技有限公司
DongGuan XunPu Electronics Co.,Ltd

TITLE: MICRO SIM H1.25

UNLESS OTHERWISE SPECIFIED TOLERANCES

PAR SMC-234-ARP10

DECIMALS: .X:±0.20 .XX:±0.10 .XXX:±0.05

ANGLES: X':±2° .X':±1° .XX':±0.5°

SCALE1:1 UNIT:MM

SIZE:A4 SHEET:1F1 REV:A

CUSTOMER COPY